

WET ETCH OF TITANIUM-TUNGSTEN FILM

ABSTRACT

A conventional and economical method to etch TiW alloys and remove the etch residues therefrom is disclosed. The composition of the present invention contains periodic acid (PIA). Such compositions, when used in optimal conditions, are effective in etching TiW alloys, and also in removing the etch residues resulting from TiW alloys. Moreover, the composition of the present invention causes relatively little etching on Al, Cu, or AlCu layers.

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